Special Issue

Soft Electronics: Materials, Devices and Applications

Message from the Guest Editors

Now, continuous research efforts are focusing on the fundamental aspect of material properties and engineering methods for flexible device fabrications, with attempts to build devices with advanced functions, compliant mechanical properties, and improved biocompatibility with various form factors to accomplish different engineering tasks, especially in the field of biomedical and clinical applications. Thus, this Special Issue intends to showcase research papers, communications, and review articles that address the latest results and progress in soft electronics and their applications, especially in the following context: (1) novel engineering strategies that improve stretchable polymers' electronic properties, including bandgap structure, electrical conductance, dielectric responses, and electromagnetic properties; (2) wearable/implantable biomedical devices with great potential to serve in future clinics for health monitoring and therapy; (3) transient devices that dissolved in a biological environment over a programmed period after operation.

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